

SEA & LAND ELECTRONIC CORP.

www.sealand-pptc.com

APPROVAL SHEET

MODEL NO.:	mSMD020-60V	
CUSTOMER:		
CUSTOMER'S APP	{OVAL:	
AUTHORIZED SIGN	ATURE/STAMP:	
DATE		
DATE		

HEAD OFFICE:	13F.,No.120-10,Sec.3,Zhongshan Rd.,Zhonghe Dist.,New Taipei City 23544,Taiwan Tel: 886-2-8221-2567 Fax:882-2-2225-7268 E-mail:service@chipfast.com.tw
Submitted by: Approved by: DATE:	Jay Chen YC Lin 2015/1/19

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mSMD020-60V

Performance Specification

						Maxi	mum	Resis	stance								
Model	V _{max}	I _{max}	I _{hold}	I _{trip}	Pd	Time To Trip				Agency Approval							
Model			@25°C	@25°C	Тур.	Current	Time	Ri _{min}	R1 _{max}	UL	τυν						
	(Vdc)	(A)	(A)	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)	UL	100						
mSMD020-60V	60.0	100	0.20	0.40	0.8	8.0	0.02	0.350	5.000								
Ihold = Hold Current.	Maximum cu	rrent device w	vill not trip in 2	5°C still air.													
Itrip = Trip Current.	Ainimum curre	ent at which th	ne device will	always trip in	25°C still air.												
Vmax = Maximum ope	erating voltage	e device can v	vithstand with	out damage a	at rated curre	nt (Imax).											
Imax = Maximum fau	Imax = Maximum fault current device can withstand without damage at rated voltage (Vmax).																
Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.																	
Rimin/max = Minimum/Maximum device resistance prior to tripping at 25°C.																	
R1 _{max} = Maximum device resistance is measured one hour post reflow.																	
CAUTION : Operation	beyond the sp	ecified rating	s may result i	n damage an	d possible ar	cing and flame			CAUTION: Operation beyond the specified ratings may result in damage and possible arcing and flame.								

Features

Surface Mount Devices

Surface Mount packaging

for automated assembly

Lead free device
 Size 4.5*3.2 mm/0.18*0.12 inch

Applications

protected, including:

Almost anywhere there is a low voltage power supply, up to 60V and a load to be

Computer mother board, Modem. USB hub

PDAs & Charger, Analog & digital line card

Digital cameras, Disk drivers, CD-ROMs,

Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-202, Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripp	ed state is 125 °C	

Agency Approvals :

UL pending

Regulation/Standard:

HS	2002/95/EC
	EN14582

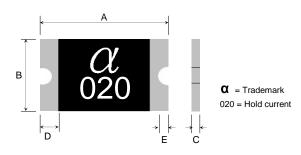
Ihold Versus Temperature

Model	Maximum ambient operating temperature (T _{mao}) vs. hold current (I _{hold})									
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C	
mSMD020-60V	0.29	0.26	0.23	0.20	0.17	0.15	0.14	0.12	0.10	

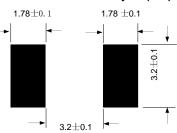
mSMD020-60V

Construction And Dimension (Unit:mm)									
Model	Α			В		С		E	
Woder	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.	
mSMD020-60V	4.37	4.73	3.07	3.41	0.50	1.30	0.30	0.25	

Dimensions & Marking



Recommended Pad Layout (mm)



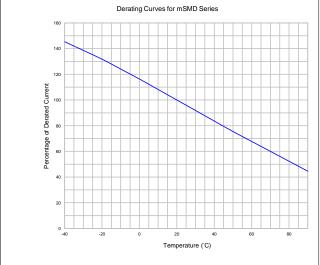
Termination Pad Characteristics

Terminal pad materials : Terminal pad solderability : Rework

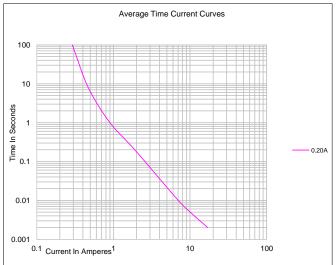
Tin-plated Nickel-Copper Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

Use standard industry practices, the removal device must be replaced with a fresh one.

Thermal Derating Curve



Typical Time-To-Trip At 25°C



🖄 WARNING:

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be use d when repeated fault conditions or prolonged trip events are

- anticipated.
 Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
 Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
 Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
 Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard

- methods. Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layou ts or reflow profile could negatively impact solderability

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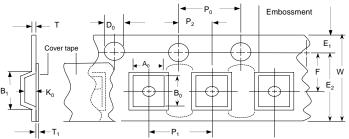
Recommended Solder Reflow Conditions Preheating Soldering Cooling невденангне(_с U) 300 250 200 190 160 100 0 60-120 sec. 30~60sec. 120 sec.

- Recommended reflow methods : IR, vapor phase oven, hot air oven. · Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- Devices can be cleaned using standard method and solvents. Note : If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

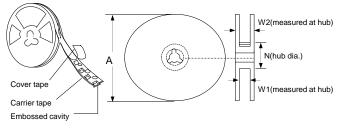
Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-1
W	12 ± 0.3
P0	4.0 ± 0.10
_P1	8.0 ± 0.10
P2	2.0 ± 0.05
_A0	3.5 ± 0.23
B0	5.1 ± 0.15
B1max.	5.9
D0 F	1.5 + 0.1, -0
<u>F</u>	5.5 ± 0.05
<u>E1</u>	1.75 ± 0.10
E2min.	10.25
Tmax.	0.6
T1max.	0.1
<u>K0</u>	0.9 ± 0.15
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	60
W1	12.4 + 2.0, -0.0
W2max.	18.4

EIA Tape Component Dimensions



EIA Reel Dimensions



Storage And Handling

- Storage conditions : 40°C max, 70% R.H.
- · Devices may not meet specified performance
- if storage conditions are exceeded.

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		Packaging
020	-60V	Tape & Reel Quantity
Hold	Max	
Current	Voltage	1,500 pcs/reel
0.20A		
	Hold Current	Hold Max Current Voltage

Tape & reel packaging per EIA481-1

Labeling Information

